

Integrated IC chip package for electronic image sensor die

(D)

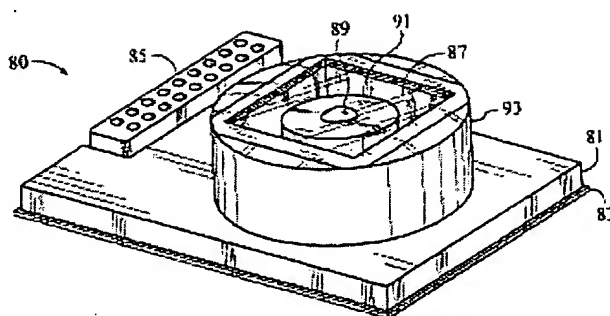
Patent number: TW501244
Publication date: 2002-09-01
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Classification:
- **international:** H01L23/28
- **europaean:**
Application number: TW20010111545 20010515
Priority number(s): US20000577201 20000523

Also published as:

WO0191193 (A:
WO0191193 (A:

Abstract of TW501244

An IC chip package for an image sensitive, integrated circuit semiconductor die incorporates all the components typically found in an imaging module of an electronic camera. The IC chip package consists of a plastic substrate base for holding an image sensor die and a separate, plastic upper cover for encapsulating the image sensor die and holding a filter glass, an optical lens, and providing an aperture for the optical lens. The upper cover has a lower shelf for holding the optical lens in alignment with the aperture opening over the image sensor die, and has an upper shelf for holding the filter glass over the optical lens. The lens is attached to the lower shelf using UV cure adhesive, and its focal distance to the image sensor die is determined by first electrically activating the image sensor die, adjusting the lens position to identify the optimal focus sharpness, and then applying UV light to activate the UV cure adhesive and hold the lens in focus.



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